

Booth No.

Invited by

The Total Solution Exhibition for Electronic Equipment 2024

INVITATION

6.12_{Wed.} → 14_{Fri.} 10:00-17:00

Tokyo Big Sight East Exhibition Halls 3-6

Managed by: **JPCA** Japan Electronics Packaging and Circuits Association

Co-operated by: **WBCE** / **CPCA** / **EIPC** / **ELCINA** / **HKPCR** / **IPC** / **IPCA** / **KPCA** / **THPCA** / **TPCA**

KPIA (Korea Packaging Integration Association) / AEIS (Association of Electronic Industries in Singapore)

No. 240612

*Please enter above No. at the visitor registration.



Overview

JPCA2024 Show

53rd International Electronic Circuits Exhibition

JIEP Microelectronics Show

38th ADVANCED ELECTRONICS PACKAGING EXHIBITION

JISSO PROTEC 2024

25th Jission Process Technology Exhibition

METaverse DEVICE EXPO
メタバースデバイス展
Metaverse Device Expo

Connecting Devices to Devices
WIRE Japan Show
Electrical /optical transmission technology

Electronics Component & Unit Show

E-Textile/Wearable
E-Textile / Wearable

Smart Sensing
Smart Sensing

無人化ソリューション展
Unmanned Solution Exhibition

Edge Computing
Edge Computing

Date: June 12 (Wed.) – 14 (Fri.), 2024

Venue: Tokyo Big Sight East Exhibition Halls 3-6

Open Hours: 10:00 – 17:00

Entrance Fee: 1,000 JPY (tax included) *Free admission with online registration

Visitor Information

Online Registration is required to visit the Total Solution Exhibition for Electronic Equipment. Please register via the official website in advance. It will not be possible to enter the exhibition with just this invitation.

STEP 1

Complete visitor registration via the official homepage

STEP 2

An email will be sent to your registered email address to set up your password. If you do not receive the password setup e-mail, please contact the Secretariat. (Secretariat E-mail: jpcashow@jtbcom.co.jp)

STEP 3

Print out the Visitor Badge from Visitor Portal and bring it with you in a four-folded format on the day you visit the exhibition.

Official Website



Check the official website for the latest information

<https://www.jpcashow.com/show2024/en/>

Access & Venue Map

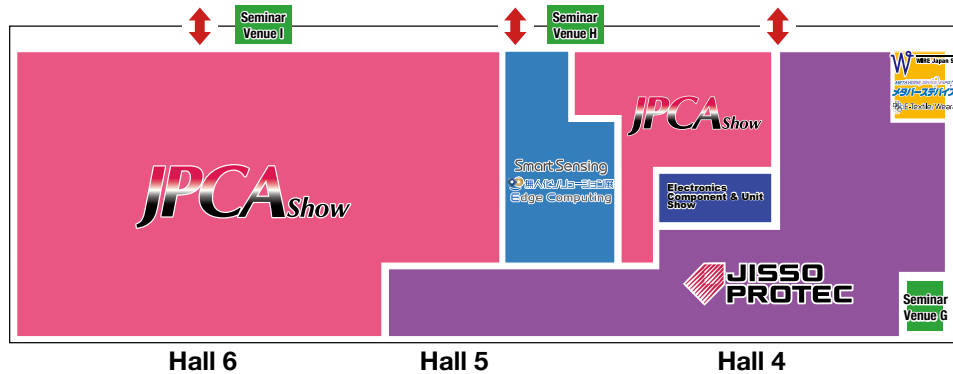
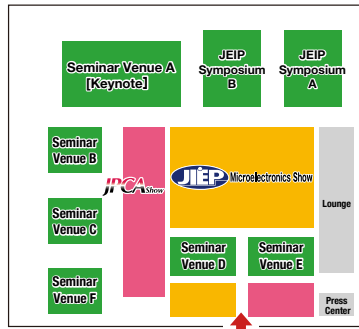


Access <https://www.bigsight.jp/english/visitor/access/>

Area Map https://www.bigsight.jp/english/download/pdf/area_map_e.pdf



Hall 3



List of Exhibitors

(As of April 15, 2024)

Sponsors

Platinum
ADTEC Engineering
MacDermid Performance Solutions Japan
MEIKO ELECTRONICS

Gold

Atotech Japan
Electro Scientific Industries Japan
Dynatron
TAIYO INK MFG
V Technology
MEC(Hyogo)

Silver

KYOSHA
Showasangyo

Bronze

JPCA Plating Committee
TOA MUSEN DENKI
NIKKAN INDUSTRIES

JPCA Show	
PWB Tech	
ADSTEC	ADTEC Engineering
AGFA Materials Japan	AIKOKIKI MFG
AIN	Akabane sangyo corporation
Albatro Tech	ALMEX TECHNOLOGIES
Altium Japan	ARGO
atg Luther & Maelzer	Athlete FA
Atotech Japan	AURONA INDUSTRIES
BEAC	BEAMS
BRUX JAPAN	C. Uyemura
Chemitox	CHEMITRON
CHEON WESTERN (CHINA) GROUP	

China Circuit Technology (Shantou)	China Printed Circuit Association (CPCA)
Chinogiken	CHOU-KOU MATERIALS
ChuangXin Japan	DAIWA
DAIWA	DDP SPECIALITY PRODUCTS JAPAN
Denka	DIC
eight kougyou	Electro Scientific Industries Japan
Electronic Circuit Pension Fund	EME
Everett/Charles Japan	FINETEK
Fischer Instruments	FUJI PRIX GROUP
FUJIKIKO	FUJIMORI KOGYO
FUKUDA METAL FOIL & POWDER	GOAL SEARCHERS, ZHUHAI
Guandong Champion Asia Electronics	HAKUTO
Hirayama Fine Techno	Hitachi High-Tech Science
Hong Kong Printed Circuit Association (HKPCA)	ICHIKAWA TECHNO FABRICS
IDAJ	Ihara Electronic Industries
inspec	IPC - Association Connecting Electronics Industries (IPC)
ISHIHARA CHEMICAL	ISHII HYOKI
JABURO INDUSTRY	Japan Circuit
Japan Electronics Packaging and Circuits Association (JPCA)	Japan Laser
JCU	Jiangsu Suhang Electronics
Jiangxi Jiangnan New Material Technology	JIANGXI LIYUAN HAINA TECHNOLOGY
J-RAS	JSR

JTDM	Kagakujouhoushupan
KANEKA	Kingboard Laminates Holdings
KITAGAWASEIKI	KONICA MINOLTA
Korea Packaging Integration Association (KPIA)	Korean Printed Circuit Association (KPCA)
Kunshan DongWei Science and Technology	KURABO INDUSTRIES
KYOEI PRINT GIKEN	KYOSHA
LPKF Laser&Electronics	Mac eight
MacDermid Performance Solutions Japan	MACOHO
MEC(Hyogo)	MEIKO ELECTRONICS
MICRO TECHNOLOGY	MicroCraft
MIKADO TECHNOS	MITSUBISHI ELECTRIC
MITSUBISHI GAS CHEMICAL COMPANY,	MOTORONICS
MURAKI	NACHI-FUJIKOSHI
NAKAJIMA CHEMICALS	NARASAKI SANGYO
NIDEC ADVANCE TECHNOLOGY	NIKKAN INDUSTRIES
NIKKO-MATERIALS	NIPPON CHEMICAL INDUSTRIAL
NITTO BOSEKI	NTW
OFUNA ENTERPRISE JAPAN	OKADA GAJ
ONTEC	ORG MANUFACTURING
ORGAN NEEDLE	Printed Circuit Journal
Pudu Robotics Japan	RAYON INDUSTRIAL
RISE ELECTRONICS	RISHO KOGYO

Rohde & Schwarz Japan	sagami pci
Sakai Chemical Industry	SAN-EI KAGAKU
Sanko Giken Kogyo	SATOSHOJI
Schmalz	Schmoll Maschinen GmbH
SCREEN PE Solutions	SHAGHAI YKC
Shandong Shengquan New Materials	SHANGHAI BLAN ELECTRONICS TECHNOLOGY
Shenzhen Han's CNC Technology	ShenZhen JCD Circuit Tech
Shenzhen JDB Technology	SHENZHEN JINZHOU PRECISION TECHNOLOGY
Shenzhen Mason Electronics	SHENZHEN NEWACCESS INDUSTRIAL
Shenzhen Technology Trust Precision Industry	SHIBUYA
SHIKOKU CHEMICALS	Shinkasei
SHINKO	Shinko Denki
Shirai Electronics Industrial:Global Sales Division	Shirai Electronics Industrial:Solutions Division
SHODA TECHTRON	Showasangyo
Sihui Fuji Electronics Technology	Smart Factory Design
Smart solution technology	SONGTEX TECHNOLOGY
Sowotech	Stella
Stella Corporation	Sunshine Global Circuits
Suntec (Toa Electronics)	Sunway Communication Japan
TAESUNG	TAI CHYANG ELECTRIC
Taiwan Printed Circuit Association (TPCA)	TAIYO INK MFG
TAKANO	Takeuchi

Tatsuta Electric Wire & Cable
Tebiki
TECHNOPRO MARUGEN
Techwise (Macao) Circuits
TESPRO
The County People's government of Xinfeng
THE JAPAN STEEL WORKS
THE NIKKAN KOGYO SHIMBUN
TIANJIN PRINTRONICS CIRCUIT
Tokyo Machine & Tool
ToTo
TOWA DIGI-TECH
TOWAPRINTKOGYO
Trojan (Suzhou) Material Technology Co., Ltd
TSK

TSUNODA BRUSH
Tulip
UNION TOOL
Ushio
V Technology
Via Mechanics
WAZAM JAPAN NEW MATERIALS
Yinghua Electronic Technology
Yiyang Jindong Technology
YMT
YOKUSUL
YUASA SYSTEM
ZEON
ZHEJIANG EMIDA PUMPS
ZHEJIANG HUANERGY

3D-MID Pavilion

EBINAX
Iwate Industrial Research Institute
Japan MID Association
Sankyokasei
TAIYO INK MFG
Wonder Future Corporation
ZUKEN

Module Japan

American Express International
Averetek
Dempa Publications
EXSEAL
Haesung DS
KIYOKAWA Plating Industry
Mitsui Chemicals ICT Materia
Mitsui Mining & Smelting
NAGASE
NAITO DENSEI KOGYO
NIPPO ELECTRONICS
Nippon Barnes
NIPPON ELECTRIC GLASS
OKUNO CHEMICAL INDUSTRIES
Oxford Instruments
Sanki Manufacturing
STAR-J
TOPPAN
Toyo Aluminium
VisasQ

Flexible Printed Circuits Products Area

HAKKOH DENSHI
Huizhou Ronai Technology
Oki Electric Cable
Shenzhen Hua Xing Si Hai Equipment
SHIIMA Electronics
Stec
TAIYO TECHNOLEX
YAMASHITAMATERIALS

EMS Japan

ASOPICS
Di-Nikko Enjineering
FUJI ELECTRONICS
Hanel Production And Import-Export Joint Stock Company
INCOM
MA-tek Japan
MEC (Kanagawa)

MOUBIC
Nichiri Manufacturing
SAKIGAKE-Semiconductor
TAHARA ELECTRIC
Toshiba Information System Japan
Advanced Packaging Technology Zone
Aztec
Marubun

Materials and Process Technology Zone for Power Semiconductors/Glass Substrates

Foresight
NICHIIWA KOGYO
High-speed Transmission Technology Zone for Automated Driving
Camelot Electronics Technology

Microelectronics Show

Addison Clear Wave Coating
RS Components
SIJTechnology
The Japan Institute of Electronics packaging (JIEP)
ViewOhre Imaging

eX-tech

AKITA CHEMICAL INDUSTRIES
Andor System Support
Athene
DENSHIGIKEN
ePrint Laboratories
ePRONICS
ESPEC
HONNY CHEMICALS
JNC Petrochemical Corporation
KANEKA TECHNO RESEARCH
Mitsuboshi Belting
NAGASE
Nippo
NORDSON
OKUNO CHEMICAL INDUSTRIES
OSAKA ORGANIC CHEMICAL INDUSTRY
Osaka Metropolitan University / Osaka Research Institute of Industrial Science and Technology
Plasma Ion Assist
SEIKO PMC
Shimada Appli
TA Instruments
TAIYO MANUFATURING
TEG SOLUTION
TOPRO TECHNO SERVICE
Toshiba Business Expert

Academic Plaza

Department of Precision Machinery Engineering, College of Science and Technology, Nihon University
Ehime University, Graduate School of Science and Engineering
Gunma University
Gunma University
Koiva Lab., Graduate School of Engineering Kanto Gakuin Univ.
Koiva Lab., Graduate School of Engineering, Kanto Gakuin Univ.
Kyushu University
Local Independent Administrative Agency Kanagawa Institute of industrial Science and Technology
Nakayama Lab., National College of Technology (KOSEN), Nagano College
Shinshu Univ
Sojo University
SUWA UNIVERSITY OF SCIENCE Organization for Regional Collaborative Research and Development
Tohoku University
Tokushima University
Tokyo Polytechnic University
Tokyo University of Science
Tokyo University of Science
Uchikoba and Kaneko Lab. Nihon Univ.
Yamagata Research Institute of Technology
YAMAGATA Univ
YOKOHAMA National University
Yokohama National University
Yonezawa Lab., Faculty of Engineering, Hokkaido Univ.

JISSO PROTEC

ALPHA ELECTRONICS
ASKK
Asyrl
ATSUGI MICRO
AYUMI INDUSTRY
Brooks Japan
CKD
DAIDO
Dynatron
EIGHTECH TECTRON
EIZO
FP INDUSTRIAL
FUJI
Gicho business communications
HAKKO
HIWIN
Japan Robot Association (JARA)
JUKI
JUTZE JAPAN
KAKEN TECH
KATO SEIKO
Kawasaki Heavy Industries
Lux electronic
MALCOM
MIRTEC JAPAN
MUSASHI ENGINEERING
NIHON SUPERIOR
NIPPON THOMPSON
OKUDA TRADING
Okuhara Electric
Panasonic Connect
PARMI JAPAN
PASSCON
PEMTRON
PROCESS LAB. MICRON
Sanoh Industrial
SAYAKA
SENJU METAL INDUSTRY
S-FINX Technologies
Shoritsu Electric Industry
TAIYO ELECTRIC IND
TAKAYA
Techno Alpha
Toyo Living
Wing Vision
YAMAHA MOTOR

METaverse Device Expo

Sangyo-times

WIRE Japan Show

KOGYO TSUSHIN
SWCC
TATSUTA Electric Wire and Cable
TOFUJI E.M.I

Electronics Component & Unit Show

CoreStaff
GLOBAL DISPLAY
HIKAWA ELECTRONICS
IIDA ELECTRONICS (TSUSHO)
JAPAN FEDERATION OF ELCTRONIC PARTS DISTRIBUTORS AND DEALERS (JEP)
JUPA
Metro Electric
NNP
NOMA ELECTRONICS
OKAMOTO ELECTRONICS
R-DENSHI
Sankyosha
SEIDENSHA

TOA MUSENDEKNI
Tokyo Electronics Appliances Wholesalers Association (TEP)
Tsuruta Seigyo Kiki








E-Textile/Wearable

SENKEN SHIMBUN

Smart Sensing Automated Solution Exhibition Edge Computing

AEMtec
AISIN TAKAOKA
Alxtal
ALPSALPINE
Canon IT Solutions
Chitose Institute of Science and Technology
City of Chitose
CONNECTEC JAPAN
CyberneX
DAIKIN FINETECH
Digi International
E-Garde
Energy Harvesting Consortium
FCL COMPONENTS
FUJIKURA COMPOSITES
FUJITOKU
Gazo
Global Information
Hort-Plan
Industrial Innovation Institute
IR System
Japan Display
Kanazawa University Vibrational Power Generator Laboratory
Keio University Haptics Research Center
KODENSHI
KRONE
Leimac
LINTEC
MARUBUN
Maxell
Micro Module Technology
Mitsunami
MODE
Mouser Electronics
NAITO DENSEI MACHIDA MFG
Narcohm
National Institute of Advanced Industrial Science and Technology, Human Augmentation Research Center
National Institute of Advanced Industrial Science and Technology, Sensing System Research Center
RoboSapiens
Robotic Increase Center
RTC
SMARTSTORE
SMK
SOFTAGENCY
SUMITOMO METAL MINING PLANNING & ADMINISTRATION DEPT. TECHNOLOGY DIV.
Tohoku University Frontier Research Institute for Interdisciplinary Sciences Shimatsu Laboratory
Tokai Rika
TOKYO ELECTRON DEVICE
TOPPAN
YAMAHA MOTOR ENGINEERING
YASHIMA ELECTRIC
Yitoe Micro Technology
Yokoyama Shokai

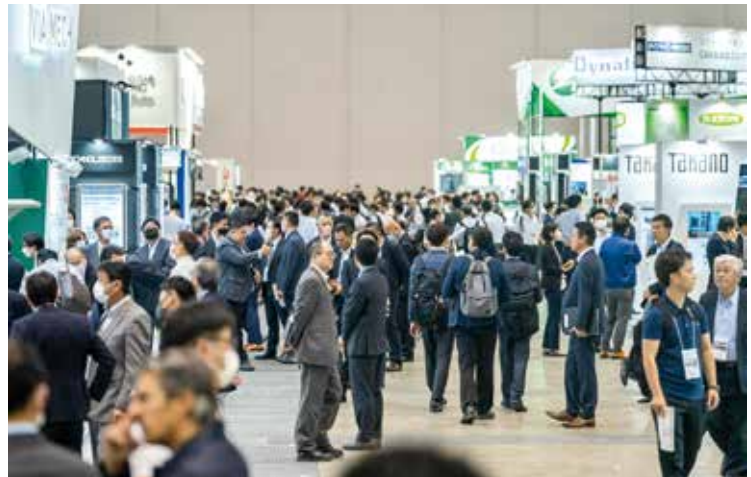
[Admission Fee] Members: Free Non-Members: 20,000JPY / 1 session *tax included *JPCA Members, JIEP Regular / Supporting / Student Members, JARA Regular / Corporate Supporting Members, JEP • TEP Members

	June 12	June 13	June 14
10:30 ~ 11:20	 <p>AI chip impact has ushered in an era of great leaps forward for semiconductors and printed circuit boards!</p> <p>Wataru Izumiya Sangyo-times, Inc</p>	 <p>spintronic low power semiconductors - For contributing to an advanced information society and low carbon society -</p> <p>Tetsuo Endoh Tohoku University Center for Innovative Integrated Electronic Systems Director / Professor Tohoku University Graduate School of Engineering Professor</p>	 <p>Accelerating Towards the Future: Rapidus Semiconductor Back-End Strategy</p> <p>Yasumitsu Orii Rapidus Corporation 3D Assembly Division Senior Managing Executive Officer</p>
11:30 ~ 12:20	 <p>The R&D situation and the development situation of devices for mobility application.</p> <p>Hiroshi Iwatsubo Murata Manufacturing Co., Ltd. Corporate Technology & Business Development Senior Executive Vice President (Board Member)</p>	 <p>Advanced Heterogeneous Integration Platform for Next Generation Computing "Road to Beyond Moore"</p> <p>Takashi Kariya Samsung Japan Corporation Samsung Device Solutions R&D Japan, Advanced Package Lab Corporate Vice President / Head of Lab</p>	 <p>The Future of AI and Robotics Fusion - Vision of Next-Generation Robots-</p> <p>Tetsuya Ogata Waseda University Institute for AI and Robotics Director</p>
12:30 ~ 13:20			 <p>Challenges on automotive E/E systems required for Software Devined Vehicles</p> <p>Takeshi Mitamura Hitachi Astemo, Ltd. SDV Platform Functional Division, Electrification Business Division Senior Vice President, Head of SDV Platform Functional Division</p>

Over 150 presentations will be given at the Total Solution Exhibition for Electronic Equipment.

For more information on the presentations, please check the website: <https://www.jpccashow.com/show2024/en/>

*Presentations will be mostly in Japanese unless otherwise shown on the website.



Managed by

Japan Electronics Packaging and Circuits Association (JPCA)

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E-mail: show@jpca.org

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Official Website

<https://www.jpccashow.com/show2024/en/>